

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Johshi GOTOH et al.

Application No.: (Divisional of 10/019,299)

Filed: Herewith

For: UNDERFILLING MATERIAL FOR SEMICONDUCTOR PACKAGE

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

Enter the instant amendment before initial examination.

Amendments to the Claims begin on page 2 of this paper.

Remarks/Arguments begin on page 4 of this paper.